

Applicant: Chi-Wei Huang, et al.
Serial No.: 10/761,881
Attorney Docket No.: 67,200-1225

REMARKS

Claims 1-20 are pending herein.

Claims 17-20 are withdrawn from consideration.

Claims 1-16 are rejected.

Claims 13-16 have been canceled.

Claims 1-9 are currently amended.

Claim Rejections under 35 U.S.C. 102

Claims 1-2, 6, 9-10 and 12-14 were rejected under 35 U.S.C. 102(b) as being anticipated by Park et al (U.S. Pat. No. 6,464,794).

It is respectfully submitted that Park et al. fails to disclose an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface...*", as set forth in claim 1 and defined by claims 2 and 6 as dependent therefrom.

It is further respectfully submitted that Park et al. fails to disclose an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface of said insert ring*", as set forth in amended claim 9 and defined by claims 10 and 12-14 as dependent therefrom.

Therefore, it is respectfully submitted that Park et al fails to anticipate claims 1-2, 6, 9-10 and 12-14 under 35 U.S.C.

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102(b). Reconsideration and allowance of claims 1-2, 6, 9-10 and 12-14 is therefore respectfully solicited.

Claims 1-2, 6, 9-10 and 12-14 were rejected under 35 U.S.C. 102(a) and 102(e) as being anticipated by Kanno et al (U.S. Pub. No. 20030029572).

It is respectfully submitted that Kanno et al. fails to disclose an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending beyond said upper step surface...", as set forth in claim 1 and defined by claims 2 and 6 as dependent therefrom.

It is further respectfully submitted that Kanno et al. fails to disclose an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending beyond said upper step surface of said insert ring", as set forth in amended claim 9 and defined by claims 10 and 12-14 as dependent therefrom.

Therefore, it is respectfully submitted that Kanno et al fails to anticipate claims 1-2, 6, 9-10 and 12-14 under 35 U.S.C. 102(a) and 102(e). Reconsideration and allowance of claims 1-2, 6, 9-10 and 12-14 is therefore respectfully solicited.

Claims 1-2, 6, 9-10 and 12 were rejected under 35 U.S.C. 102(a) and 102(e) as being anticipated by Koshiishi et al (U.S.

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Pub. No. 20030106647).

It is respectfully submitted that Koshiishi et al. fails to disclose an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface...*", as set forth in claim 1 and defined by claims 2 and 6 as dependent therefrom.

It is further respectfully submitted that Koshiishi et al. fails to disclose an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface of said insert ring*", as set forth in amended claim 9 and defined by claims 10 and 12 as dependent therefrom.

Therefore, it is respectfully submitted that Koshiishi et al. fails to anticipate claims 1-2, 6, 9-10 and 12 under 35 U.S.C. 102(a) and 102(e). Reconsideration and allowance of claims 1-2, 6, 9-10 and 12 is therefore respectfully solicited.

Claims 1-2, 6, 9-10 and 12-14 were rejected under 35 U.S.C. 102(a) and 102(e) as being anticipated by Ma et al (U.S. Pub. No. 20030106646).

It is respectfully submitted that Ma et al. fails to disclose an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface...*", as set forth in claim 1 and defined by claims 2 and 6

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as dependent therefrom.

It is further respectfully submitted that Ma et al. fails to disclose an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface of said insert ring*", as set forth in amended claim 9 and defined by claims 10 and 12-14 as dependent therefrom.

Therefore, it is respectfully submitted that Ma et al fails to anticipate claims 1-2, 6, 9-10 and 12-14 under 35 U.S.C. 102(a) and 102(e). Reconsideration and allowance of claims 1-2, 6, 9-10 and 12-14 is therefore respectfully solicited.

Claims 1-2, 6, 9-10 and 12 were rejected under 35 U.S.C. 102(a) and 102(e) as being anticipated by Morikage et al (U.S. Pub. No. 20030066484).

It is respectfully submitted that Morikage et al. fails to disclose an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface...*", as set forth in claim 1 and defined by claims 2 and 6 as dependent therefrom.

It is further respectfully submitted that Morikage et al. fails to disclose an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said*

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upper step surface of said insert ring", as set forth in amended claim 9 and defined by claims 10 and 12 as dependent therefrom.

Therefore, it is respectfully submitted that Morikage et al fails to anticipate claims 1-2, 6, 9-10 and 12 under 35 U.S.C. 102(a) and 102(e). Reconsideration and allowance of claims 1-2, 6, 9-10 and 12 is therefore respectfully solicited.

Claims 1-2, 6, 9-10 and 12 were rejected under 35 U.S.C. 102(b) as being anticipated by Hao et al (U.S. Pub. No. 20020059981).

It is respectfully submitted that Hao et al. fails to disclose an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface*...", as set forth in claim 1 and defined by claims 2 and 6 as dependent therefrom.

It is further respectfully submitted that Hao et al. fails to disclose an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface of said insert ring*", as set forth in amended claim 9 and defined by claims 10 and 12 as dependent therefrom.

Therefore, it is respectfully submitted that Hao et al fails to anticipate claims 1-2, 6, 9-10 and 12 under 35 U.S.C. 102(b). Reconsideration and allowance of claims 1-2, 6, 9-10 and 12 is therefore respectfully solicited.

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Claims 1-2, 6, 9-10 and 12-14 were rejected under 35 U.S.C. 102(b) as being anticipated by Nagaiwa et al (U.S. Pub. No. 20020029745).

It is respectfully submitted that Nagaiwa et al. fails to disclose an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending beyond said upper step surface...", as set forth in claim 1 and defined by claims 2 and 6 as dependent therefrom.

It is further respectfully submitted that Nagaiwa et al. fails to disclose an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending beyond said upper step surface of said insert ring", as set forth in amended claim 9 and defined by claims 10 and 12-14 as dependent therefrom.

Therefore, it is respectfully submitted that Nagaiwa et al fails to anticipate claims 1-2, 6, 9-10 and 12-14 under 35 U.S.C. 102(b). Reconsideration and allowance of claims 1-2, 6, 9-10 and 12-14 is therefore respectfully solicited.

Claims 1-2, 6, 9-10 and 12 were rejected under 35 U.S.C. 102(e) as being anticipated by Tamura et al (U.S. Pat. No. 6,815,352).

It is respectfully submitted that Tamura et al. fails to disclose an insert ring assembly comprising "an insert ring...an

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upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending *beyond said upper step surface...*", as set forth in claim 1 and defined by claims 2 and 6 as dependent therefrom.

It is further respectfully submitted that Tamura et al. fails to disclose an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending *beyond said upper step surface of said insert ring*", as set forth in amended claim 9 and defined by claims 10 and 12 as dependent therefrom.

Therefore, it is respectfully submitted that Tamura et al fails to anticipate claims 1-2, 6, 9-10 and 12 under 35 U.S.C. 102(e). Reconsideration and allowance of claims 1-2, 6, 9-10 and 12 is therefore respectfully solicited.

Claim Rejections under 35 U.S.C 103

Claims 3-5, 7-8, 11 and 15-16 were rejected under 35 U.S.C. 103(a) as being unpatentable over Park et al. (U.S. Pat. No. 6,464,794).

It is respectfully submitted that Park et al fails to teach or suggest an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending *beyond said upper step surface...*", as set forth in claim 1 and defined by claims 3-5 and 7-8 as dependent therefrom.

It is further respectfully submitted that Park et al fails

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to teach or suggest an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface of said insert ring*", as set forth in amended claim 9 and defined by claims 11 and 15-16 as dependent therefrom.

Therefore, it is respectfully submitted that Park et al fails to render claims 3-5, 7-8, 11 and 15-16 obvious within the contemplation of 35 U.S.C. 103(a). Reconsideration and allowance of claims 3-5, 7-8, 11 and 15-16 is therefore respectfully solicited.

Claims 3-5, 7-8, 11 and 15-16 were rejected under 35 U.S.C. 103(a) as being unpatentable over Koshiishi et al. (U.S. Pub. No. 20030106647).

It is respectfully submitted that Koshiishi et al fails to teach or suggest an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending beyond said upper step surface*...", as set forth in claim 1 and defined by claims 3-5 and 7-8 as dependent therefrom.

It is further respectfully submitted that Koshiishi et al fails to teach or suggest an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and *extending*

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beyond said upper step surface of said insert ring", as set forth in amended claim 9 and defined by claims 11 and 15-16 as dependent therefrom.

Therefore, it is respectfully submitted that Koshiishi et al fails to render claims 3-5, 7-8, 11 and 15-16 obvious within the contemplation of 35 U.S.C. 103(a). Reconsideration and allowance of claims 3-5, 7-8, 11 and 15-16 is therefore respectfully solicited.

Claims 3-5, 7-8, 11 and 15-16 were rejected under 35 U.S.C. 103(a) as being unpatentable over Tamura et al. (U.S. Pat. No. 6,815,352).

It is respectfully submitted that Tamura et al fails to teach or suggest an insert ring assembly comprising "an insert ring...an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending *beyond said upper step surface...*", as set forth in claim 1 and defined by claims 3-5 and 7-8 as dependent therefrom.

It is further respectfully submitted that Tamura et al fails to teach or suggest an insert ring assembly comprising "a wafer support...an insert ring encircling said wafer support...an annular step having an upper step surface provided on [a] ring body...a shadow ring encircling said insert ring and extending *beyond said upper step surface of said insert ring*", as set forth in amended claim 9 and defined by claims 11 and 15-16 as dependent therefrom.

Therefore, it is respectfully submitted that Tamura et al

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fails to render claims 3-5, 7-8, 11 and 15-16 obvious within the contemplation of 35 U.S.C. 103(a). Reconsideration and allowance of claims 3-5, 7-8, 11 and 15-16 is therefore respectfully solicited.

Conclusion

Every effort has been made to amend applicant's claims in order to define his invention in the scope to which it is entitled. Accordingly, reconsideration and allowance of claims 1-16 is respectfully solicited.

Respectfully submitted,



Randy W. Tung
Tung & Associates
Reg. No. 31,311